IPC-A-600H Errata Information – August 2010 (These corrections should be made in user's hard copies in accordance with the company's documented control program)

Sections are in red, instructional text in green, and corrections in black.

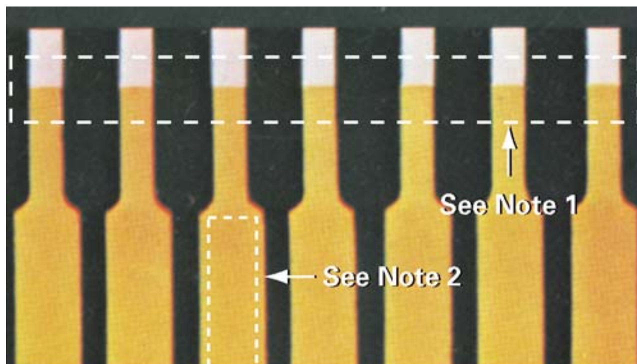
2.3.4 Foreign Inclusions

Replace acceptance criteria for Class 1, 2 and 3 with:

Acceptable – Class 1, 2, 3
• Translucent particles trapped within the printed board.
• Opaque particles trapped within the printed board which do not reduce the spacing between adjacent conductors to below the minimum spacing specified.
• Electrical parameters of the printed board are unaffected.

2.7.1 Surface Plating – Plated Contacts

Replace Figure 271a with:



2.9.6 Waves/Wrinkles/Ripples

Replace acceptance criteria for Class 1, 2 and 3 with:

Acceptable - Class 1, 2, 3
• Waves or ripples in the solder mask do not reduce the solder mask coating thickness below the minimum thickness requirements (when specified).
• Wrinkling is located in an area that does not bridge conductive patterns and meets IPC-6010 requirements for solder mask adhesion.

3.3.9 Copper Wrap Plating

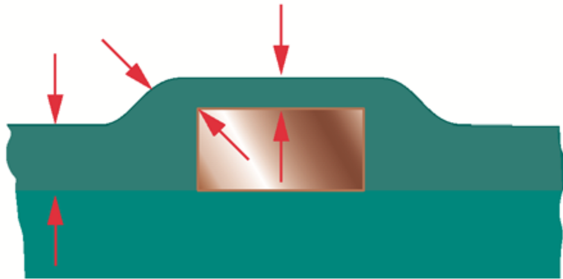
Replace acceptance criteria for Class 1, 2 with:

Acceptable - Class 2
• Wrap plating is continuous from the filled plated hole onto the external surface.
• Wrap thickness is not less than 5 µm [197 µin] for all through-hole and via structures.
• Reduction of surface wrap copper plating by processing (sanding, etching, planarization, etc.) does not result in insufficient wrap plating.

Acceptable - Class 1
• Wrap thickness **shall** be AABUS.

3.3.12 Solder Mask Thickness

Replace Figure 3312b with:



3.3.16 Material Fill of Blind and Buried Vias

Replace acceptance criteria for Class 1, 2 and 3 with:

Acceptable – Class 2, 3
• At least 60% buried via fill with laminating resin or similar fill material.

Acceptable – Class 2, 3
• At least 60% fill for blind vias with an aspect ratio greater than 1:1 or as specified in the procurement documentation.

Acceptable - Class 1
• Blind and buried vias may be completely void of fill material.

4.1.2.1 Adhesive Squeeze-Out – Land Area

Replace acceptance criteria for Class 1 with:

Acceptable – Class 1
•A solderable annular ring for at least 240°of the circumference.